

Temperature increase of main components

Model: MGW324□□

1. Conditions

- (1) Input :DC 24 [V]
 (2) Output :Rated output
 (3) Cooling method :Convection cooling
 (4) Mounting method :Shown as Fig.1.1

2. Result

Table 2.1 Temperature increase of main components

No.	Parts name	Symbol No.	Increase (ΔT)		Rated temp. [°C]	Reference
			[deg]			
			±12V	±15V		
1	Switching MOS-FET	TR11	26	24	150	Junction Temp.
2	Switching MOS-FET	TR101	29	27	150	Junction Temp.
3	Power control IC	IC11	26	23	150	Junction Temp.
4	Rectified diode (Output)	D201	30	27	150	Junction Temp.
5	Rectified diode (Output)	D202	33	28	150	Junction Temp.
6	Photocoupler	PC11	26	23	125	Junction Temp.
7	Transformer (PCB)	P2	29	27	130	
8	CASE	CASE	26	24	110	Top Surface Center
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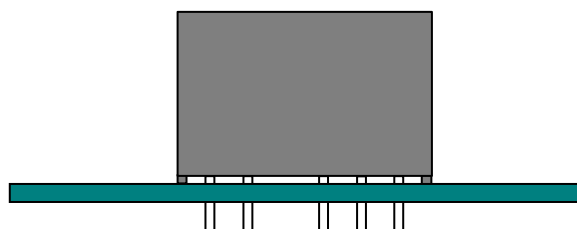


Fig.1.1 Mounting method